



**Zepoxy Electroflex** is a specially designed electronic component potting adhesive which gives a clear, bubble-free finish with high flexibility.

## TECHNICAL DATA

Property	Test Method	Result
Appearance Part A	-	Clear liquid
Appearance Part B	-	Clear liquid
Viscosity @ 25°C Part A	ASTM D 2196-05	2,000 – 3,500
Viscosity @ 25°C Part B	ASTM D 2196-05	100 – 200
Mix ratio (Part A: Part B)	ASTM D 2074	100: 100
Pot life (300g mix) @ 30°C	-	40m
Gel time (20g mix) @ 30°C	-	3h
Mix density @ 30°C	ASTM D 1475-98	1.10 g/cc

These are typical results under laboratory conditions, actual coverage and timings may vary as per actual working environment.

## USAGE GUIDELINE

Add Part A and Part B and mix at medium speed for 5 minutes, carefully so that bubbles are not produced. After pouring the mix in the electronic components, the foam generated will be finish after some time without any agitation or intervention, incase the bubbles persist, flame torch can be used. Once the epoxy is tack-free, for superior final performance post-cure it at an elevated temperature for 2-4 hours.

## PACKAGING

**Zepoxy Electroflex** is available as follows:

2 KG Sets      Part A: 1 KG  
                    Part B: 1 KG

30 KG Sets     Part A: 15KG  
                    Part B: 15 KG

## HEALTH AND SAFETY

Dispose containers of the materials as per local laws, rules, and regulations. Use gloves, safety masks and other safety apparel as per health and safety laws. For further assistance, please refer to the MSDS of the product for further health and safety information.